

Abstract of the Disclosure

The present invention provides a semiconductor device comprising a substrate, a semiconductor chip mounted on the substrate, external electrodes placed on the back of the substrate and for connecting electrodes of the semiconductor chip to the outside, a sealing member for encapsulating the semiconductor chip on the substrate, and a heat sink plate fixed with the sealing member. In the semiconductor device, the heat sink plate is disposed so as to be opposed to a main surface on which semiconductor elements of the semiconductor chip are formed.

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